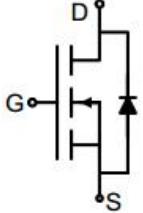


## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The GT070N15M uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> 150V</li> <li>● <math>I_D</math> (at <math>V_{GS} = 10V</math>) 140A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 10V</math>) &lt; 5.8mΩ</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	 <p>Schematic diagram</p>  <p>TO-263</p>
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### Ordering Information

Device	Package	Marking	Packaging
GT070N15M	TO-263	GT070N15	800pcs/Reel

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Continuous Drain Current	$I_D$	140	A
Pulsed Drain Current (note1)	$I_{DM}$	560	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	320	W
Single pulse avalanche energy (note2)	$E_{AS}$	420	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	°C

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	55	°C/W
Maximum Junction-to-Case	$R_{thJC}$	0.39	°C/W

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	150	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	--	4.8	5.8	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{GS}} = 5\text{V}, I_D = 30\text{A}$	--	35	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 75\text{V}, f = 0.5\text{MHz}$	--	5850	--	pF
Output Capacitance	$C_{\text{oss}}$		--	610	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	8	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 75\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	--	89	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	32	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	19	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 75\text{V}, I_D = 30\text{A}, R_G = 4.7\Omega$	--	17	--	ns
Turn-on Rise Time	$t_r$		--	70	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	47	--	
Turn-off Fall Time	$t_f$		--	15	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	140	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 30\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F = 30\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	146	--	nC
Reverse Recovery Time	$T_{\text{rr}}$		--	63	--	ns

**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$

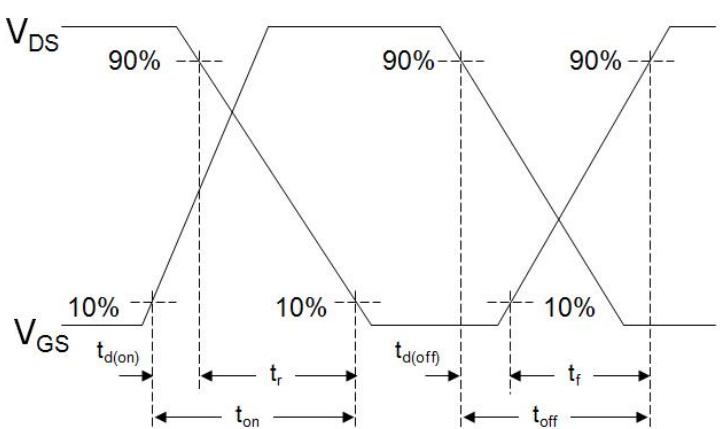
The table shows the minimum avalanche energy, which is 1156mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

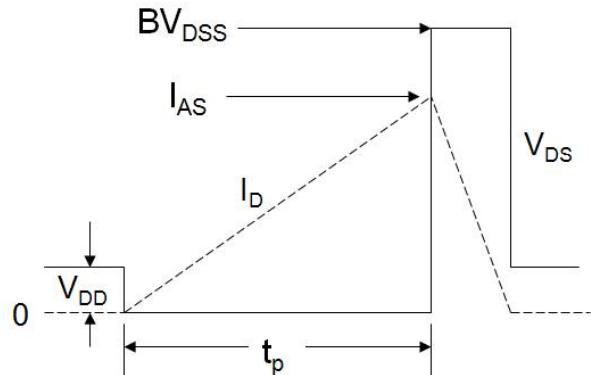
### Gate Charge Test Circuit



### Switch Time Test Circuit

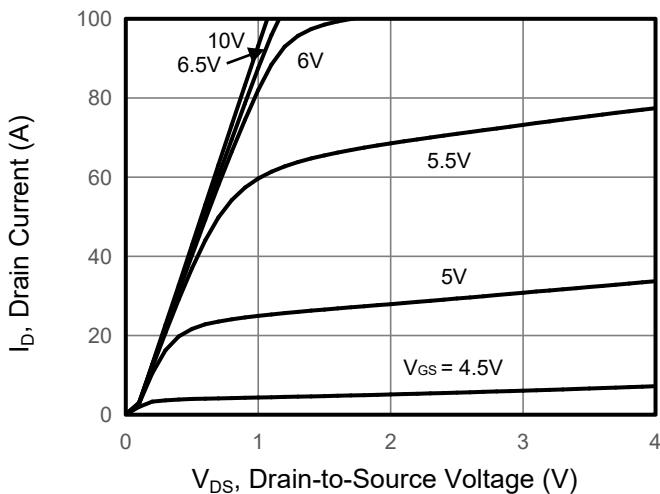


### EAS Test Circuit

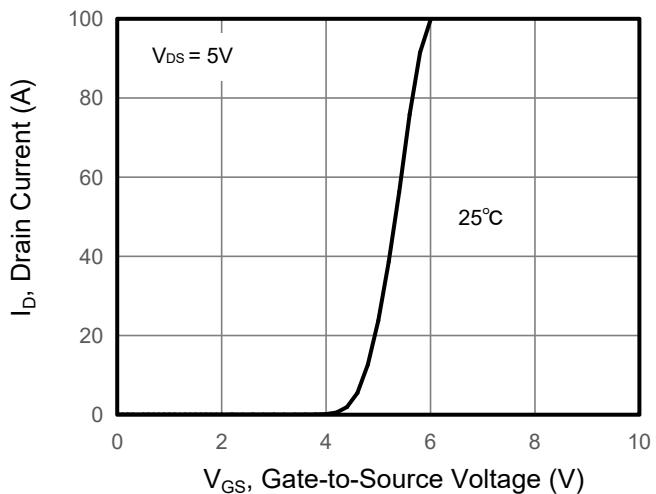


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

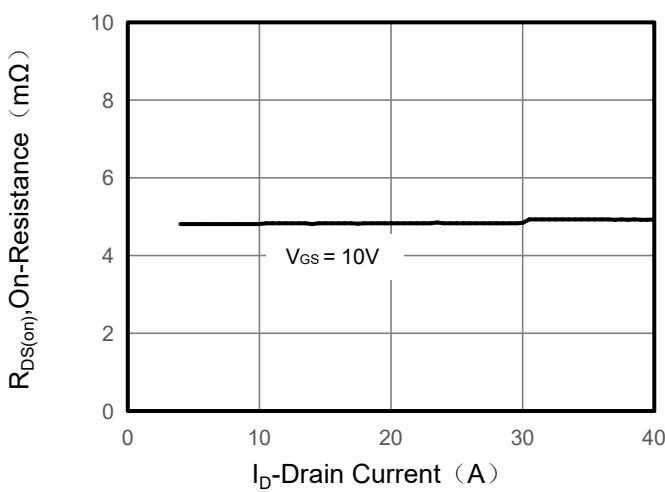
**Figure 1. Output Characteristics**



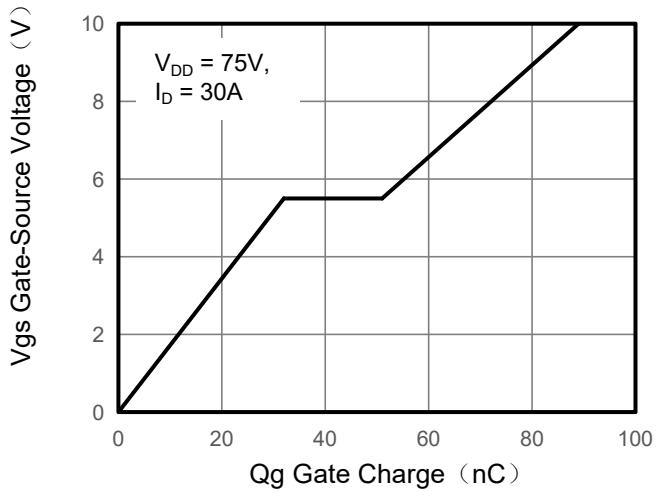
**Figure 2. Transfer Characteristics**



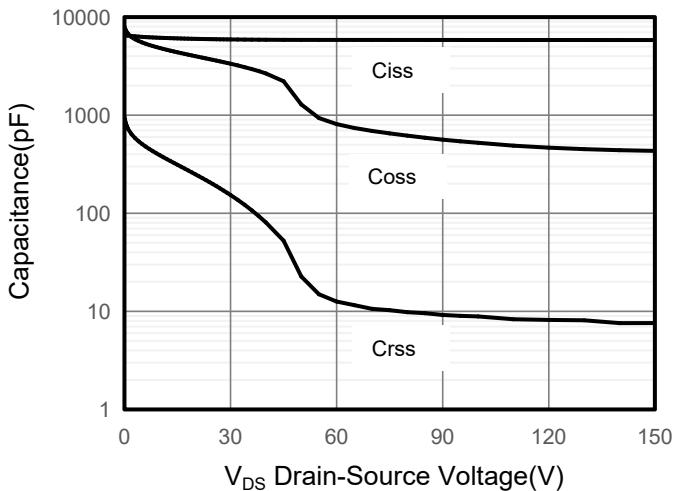
**Figure 3. Drain Source On Resistance**



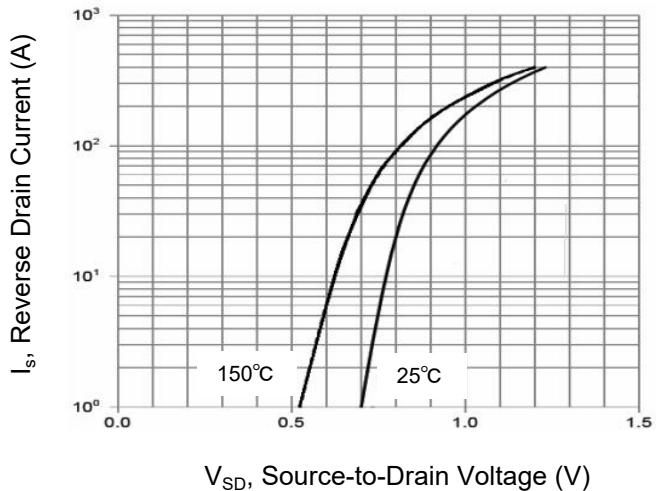
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

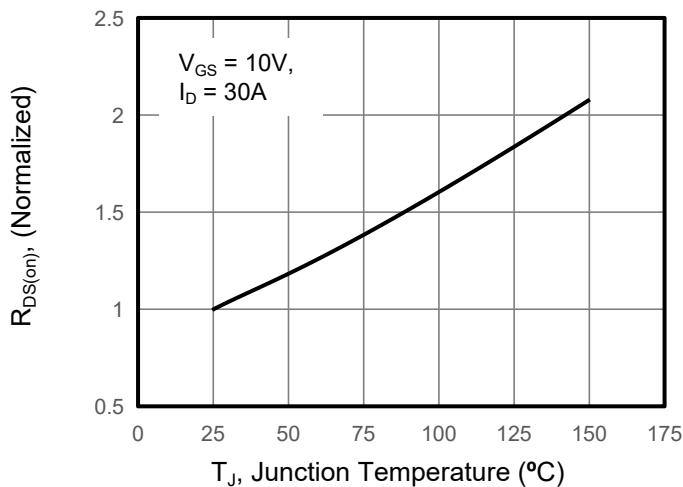


**Figure 6. Source-Drain Diode Forward**

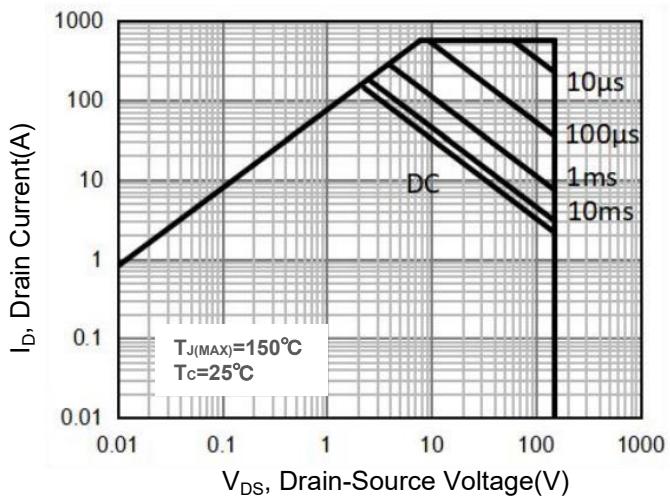


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

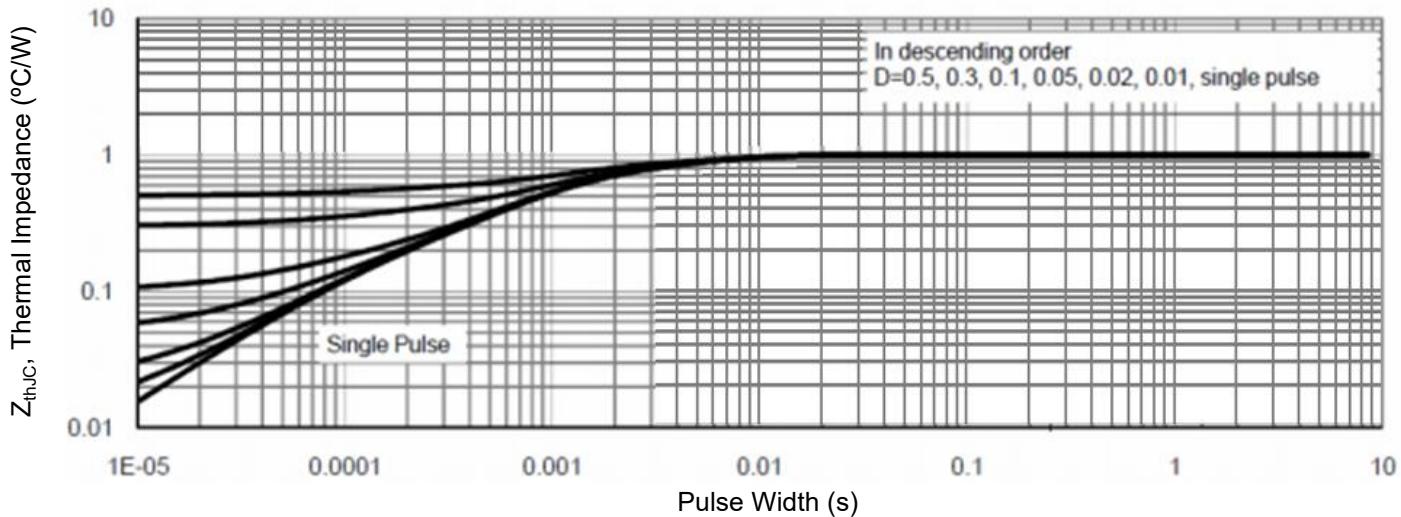
**Figure 7. Drain-Source On-Resistance**



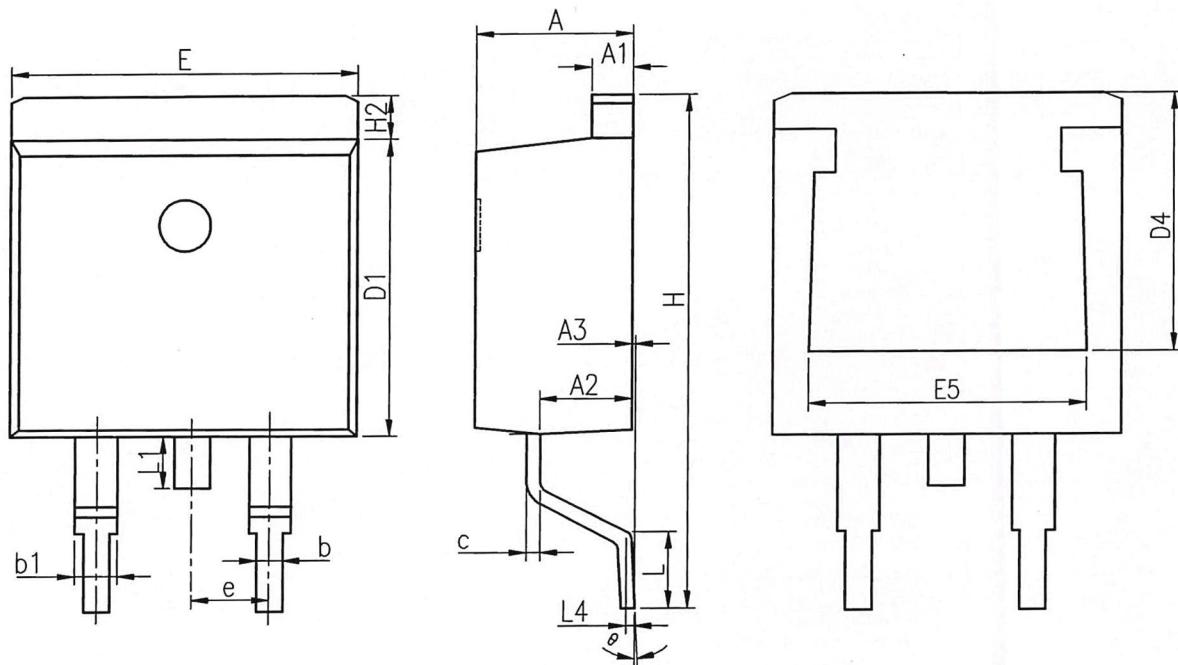
**Figure 8. Safe Operation Area**



**Figure 9. Normalized Maximum Transient Thermal Impedance**



## TO-263 Package Information



## COMMON DIMENSIONS

SYMBOL	MM			SYMBOL	MM		
	MIN	NOM	MAX		MIN	NOM	MAX
A	4.37	4.57	4.77	E	9.86	10.16	10.36
A1	1.22	1.27	1.42	E5	7.06	-	-
A2	2.49	2.69	2.89	e	2.54 BSC		
A3	0.00	0.13	0.25	H	14.70	15.10	15.50
b	0.70	0.81	0.96	H2	1.07	1.27	1.47
b1	1.17	1.27	1.47	L	2.00	2.30	2.60
c	0.30	0.38	0.53	L1	1.40	1.55	1.70
D1	8.50	8.70	8.90	L4	0.25 BSC		
D4	6.60	-	-	θ	0°	5°	9°